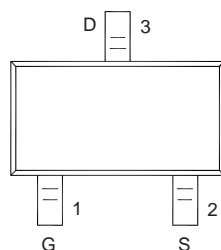


P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^{a, b}	Q_g (Typ.)
- 30	0.088 at $V_{GS} = - 10$ V	- 2.7	4.1 nC
	0.130 at $V_{GS} = - 4.5$ V	- 2.2	

(SOT-23-3L)



Top View
DTS3401

FEATURES

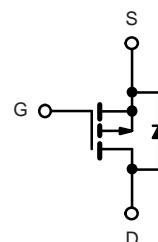
- Halogen-free Option Available
- TrenchFET[®] Power MOSFET

APPLICATIONS

- Load Switch for Portable Devices



RoHS
COMPLIANT



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150$ °C) ^{a, b}	$T_C = 25$ °C	- 3.5	A
	$T_C = 70$ °C	- 2.8	
	$T_A = 25$ °C	- 2.7 ^{a, b}	
	$T_A = 70$ °C	- 2.2 ^{a, b}	
Pulsed Drain Current (10 μ s Pulse Width)	I_{DM}	- 12	
Continuous Source-Drain Diode Current ^{a, b}	$T_C = 25$ °C	- 1.5	
	$T_A = 25$ °C	- 0.91 ^{a, b}	
Maximum Power Dissipation ^{a, b}	$T_C = 25$ °C	1.8	W
	$T_C = 70$ °C	1.14	
	$T_A = 25$ °C	1.1 ^{a, b}	
	$T_A = 70$ °C	0.7 ^{a, b}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) ^c		260	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, c}	R_{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	R_{thJF}	55	70	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. $t = 5$ s.

c. Maximum under Steady State conditions is 166 °C/W.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 32		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1		- 3	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			- 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ 5 V, V _{GS} = - 10 V	- 6			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 3.5 A		0.073	0.088	Ω
		V _{GS} = - 4.5 V, I _D = - 2.5 A		0.110	0.138	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 10 V, I _D = - 3.5 A		7		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		340		pF
Output Capacitance	C _{oss}			67		
Reverse Transfer Capacitance	C _{rss}			51		
Total Gate Charge	Q _g	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 2.5 A		4.1	6.2	nC
Gate-Source Charge	Q _{gs}			1.3		
Gate-Drain Charge	Q _{gd}			1.8		
Gate Resistance	R _g	f = 1 MHz		10		Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 15 V, R _L = 15 Ω I _D ≅ - 1 A, V _{GEN} = - 4.5 V, R _g = 1 Ω		40	60	ns
Rise Time	t _r			40	60	
Turn-Off Delay Time	t _{d(off)}			20	40	
Fall Time	t _f			17	30	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 15 V, R _L = 15 Ω I _D ≅ - 1 A, V _{GEN} = - 10 V, R _g = 1 Ω		5.5	10	
Rise Time	t _r			13	25	
Turn-Off Delay Time	t _{d(off)}			17	30	
Fall Time	t _f			7.7	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.5	A
Pulse Diode Forward Current	I _{SM}				- 12	
Body Diode Voltage	V _{SD}	I _S = - 0.75 A, V _{GS} = 0 V		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 2.5 A, dI/dt = 100 A/μs, T _J = 25 °C		17	30	ns
Body Diode Reverse Recovery Charge	Q _{rr}			11	20	nC
Reverse Recovery Fall Time	t _a			12		ns
Reverse Recovery Rise Time	t _b			5		

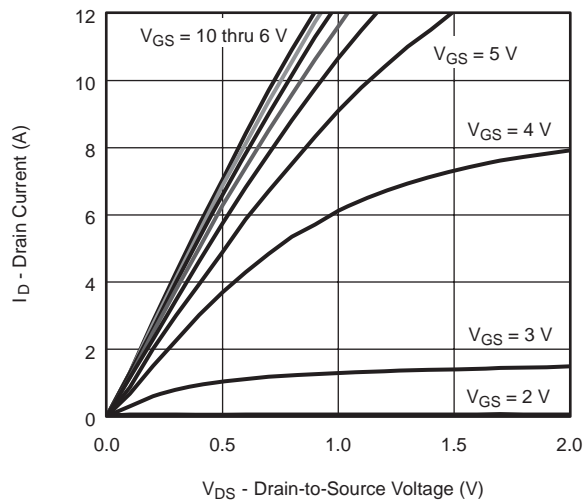
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

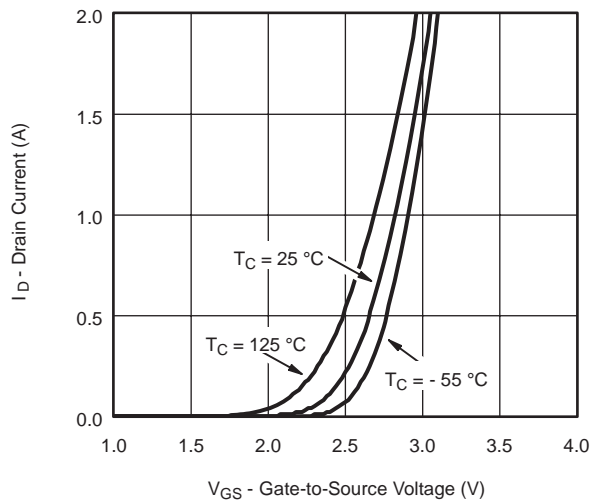
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

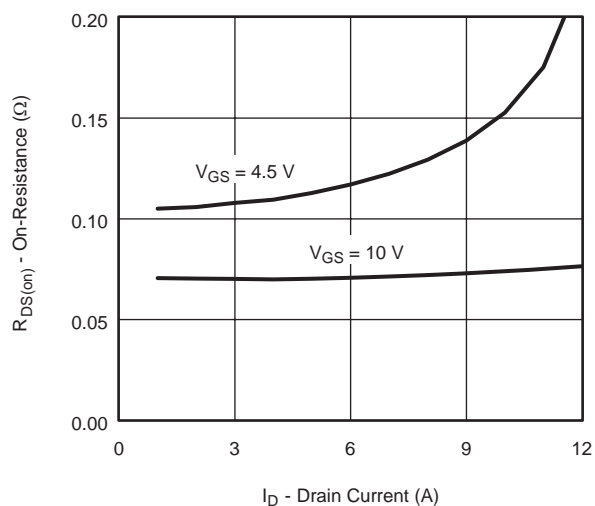
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



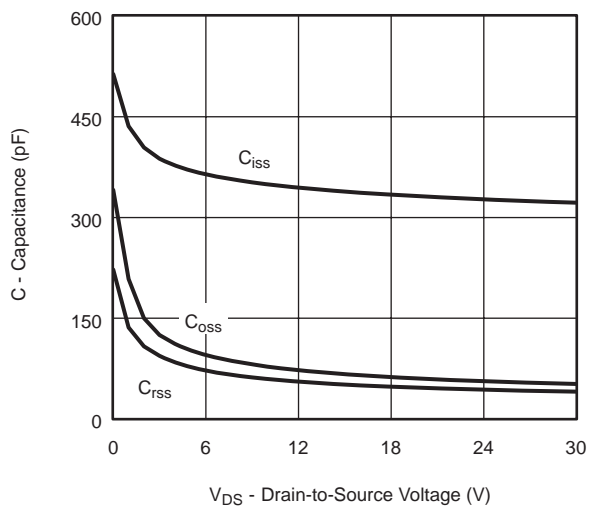
Output Characteristics



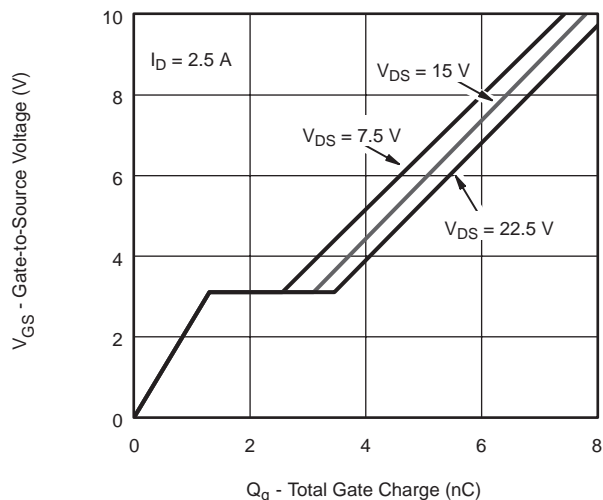
Transfer Characteristics



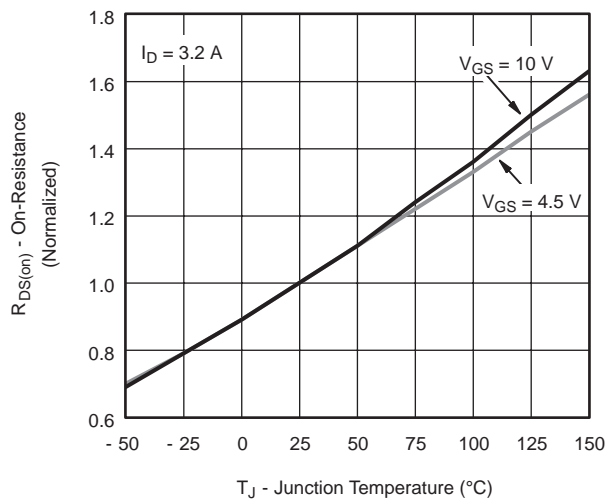
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

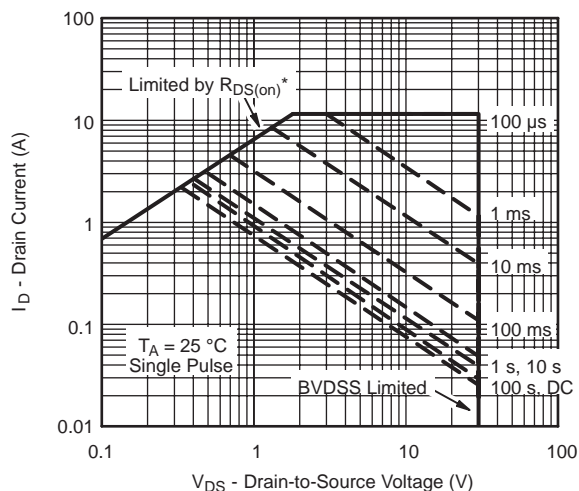
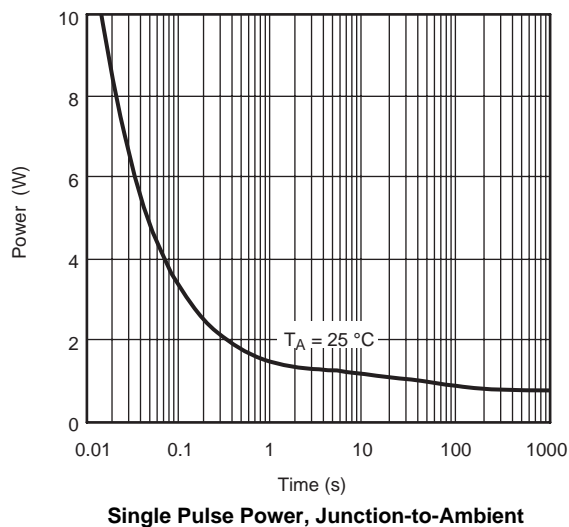
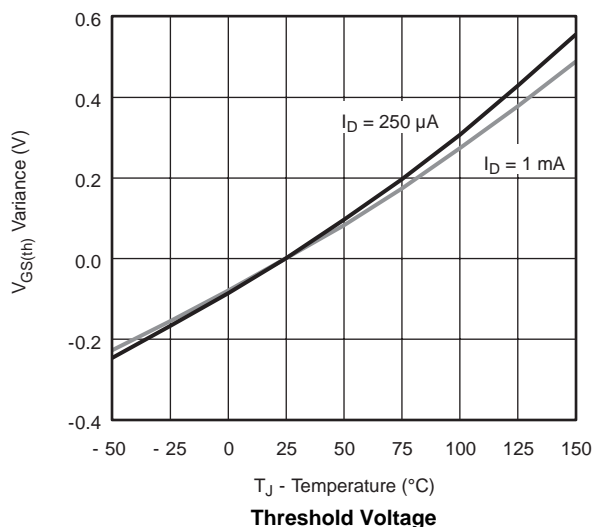
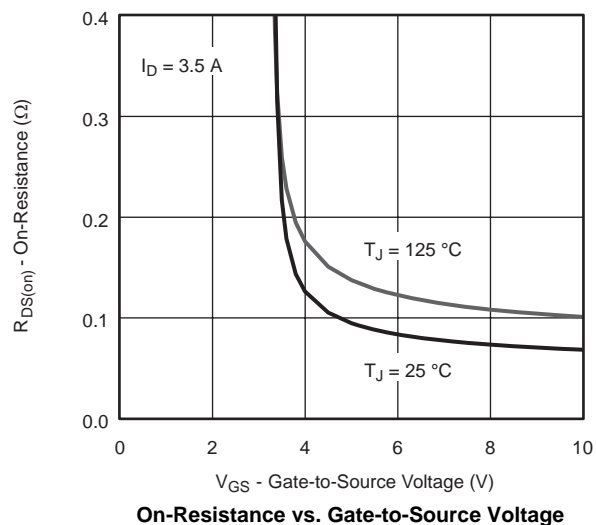
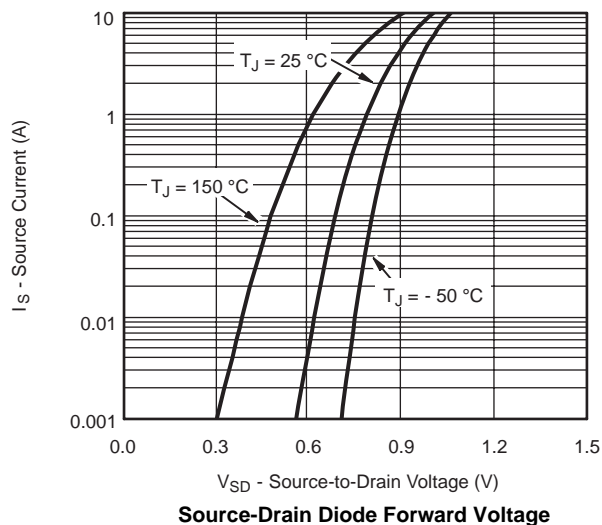


Gate Charge



On-Resistance vs. Junction Temperature

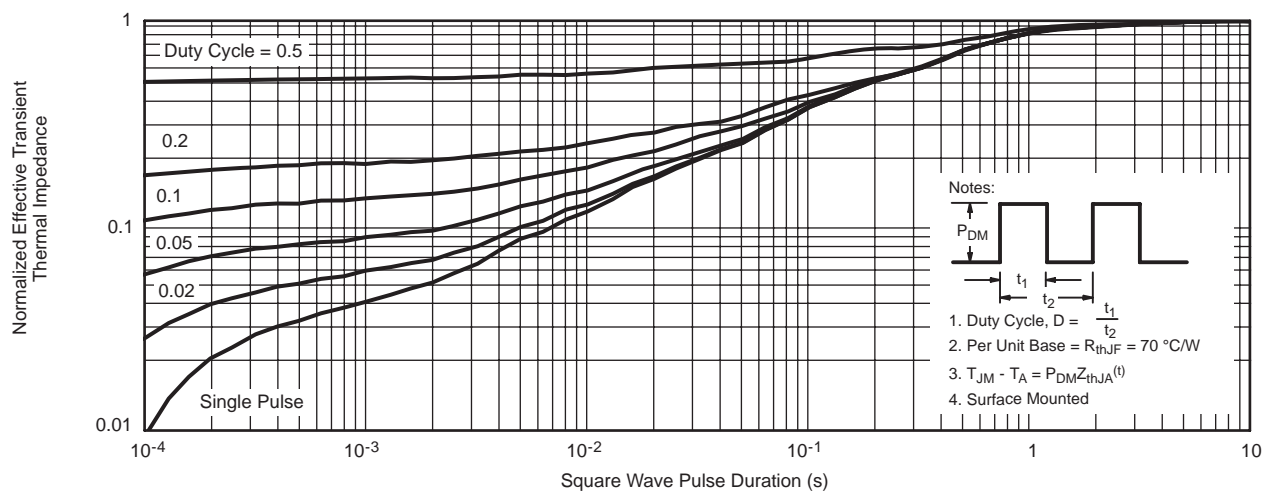
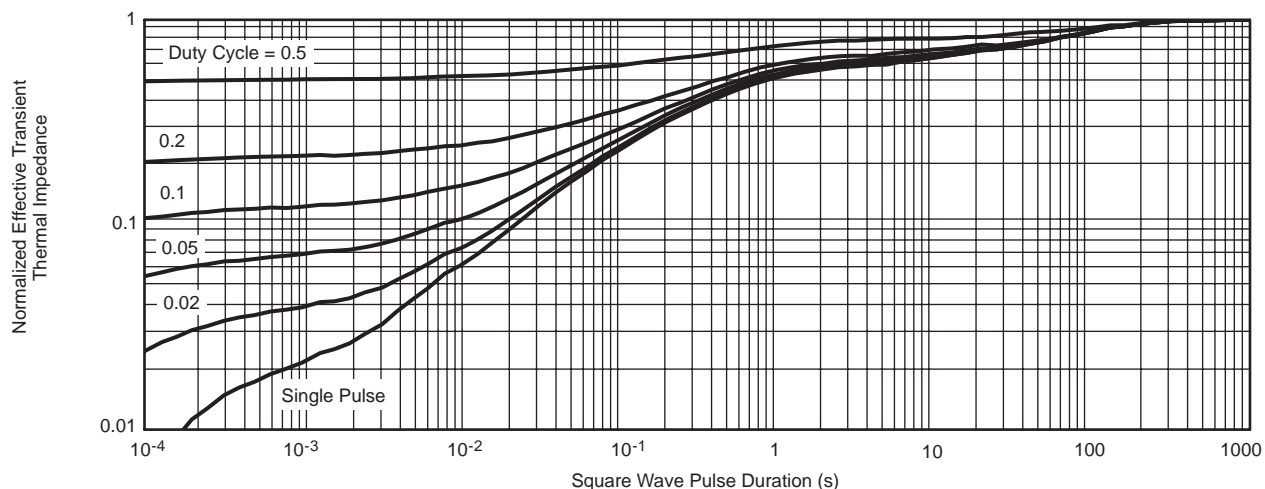
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

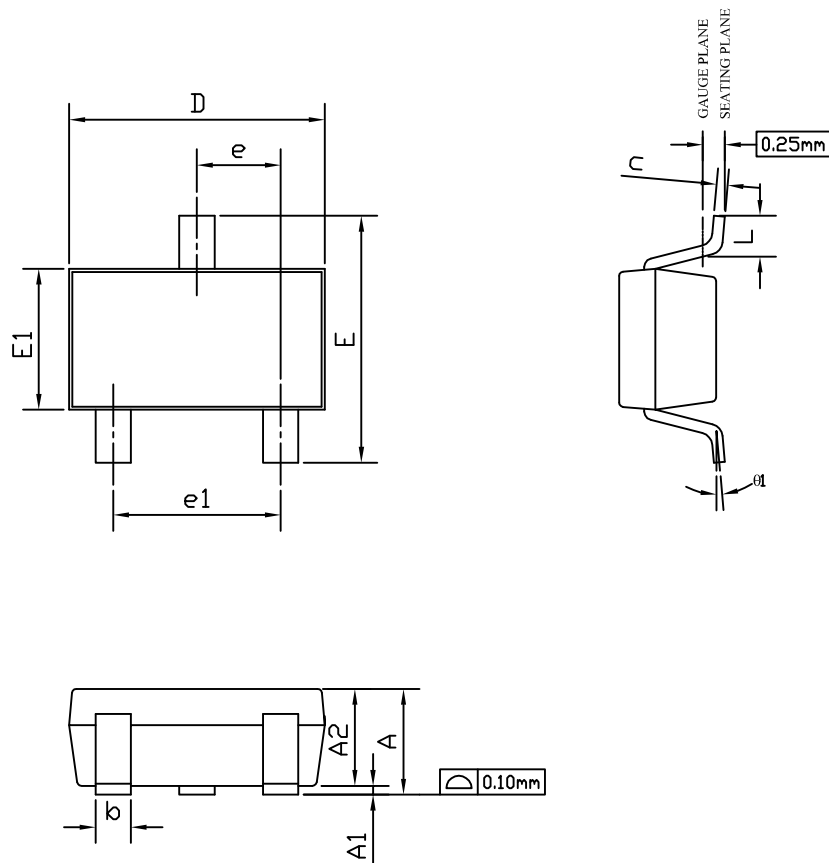


Normalized Thermal Transient Impedance, Junction-to-Foot

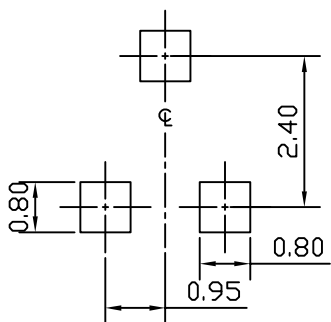
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Foot ($25\text{ }^{\circ}\text{C}$)
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

SOT-23-3L PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	—	1.25	0.033	—	0.049
A1	0.00	—	0.13	0.000	—	0.005
A2	0.70	1.00	1.15	0.028	0.039	0.045
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0.08	0.13	0.20	0.003	0.005	0.008
D	2.80	2.90	3.10	0.110	0.114	0.122
E	2.60	2.80	3.00	0.102	0.110	0.118
E1	1.40	1.60	1.80	0.055	0.063	0.071
e	0.95 BSC			0.037 BSC		
e1	1.90 BSC			0.075 BSC		
L	0.30	—	0.60	0.012	—	0.024
θ1	0°	5°	8°	0°	5°	8°

NOTE

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH OR GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 5 MILS EACH.
2. TOLERANCE ± 0.100 mm (4 mil) UNLESS OTHERWISE SPECIFIED.
3. DIMENSION L IS MEASURED IN GAUGE PLANE.
4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
5. ALL DIMENSIONS ARE IN MILLIMETERS.

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